

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

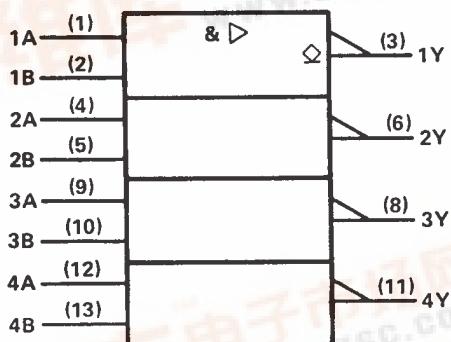
These devices contain four independent 2-input NAND buffer gates with open-collector outputs. The open-collector outputs require pull-up resistors to perform correctly. They may be connected to other open-collector outputs to implement active-low wired-OR or active-high wired-AND functions. Open-collector devices are often used to generate high V_{OH} levels.

The SN5438, SN54LS38, and SN54S38 are characterized for operation over the full military temperature range of -55°C to 125°C . The SN7438, SN74LS38, and SN74S38 are characterized for operation from 0°C to 70°C .

FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

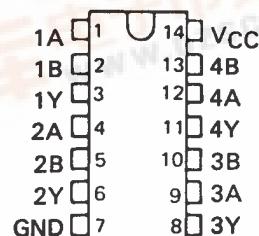
Pin numbers shown are for D, J, N, and W packages.

SN5438, SN54LS38, SN54S38 . . . J OR W PACKAGE

SN7438 . . . N PACKAGE

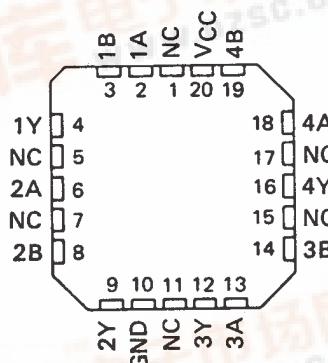
SN74LS38, SN74S38 . . . D OR N PACKAGE

(TOP VIEW)



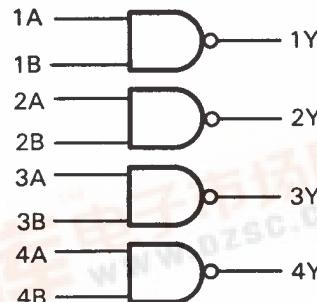
SN54LS38, SN54S38 . . . FK PACKAGE

(TOP VIEW)



NC - No internal connection

logic diagram



positive logic

$$Y = \overline{A} \cdot \overline{B} \text{ or } Y = \overline{A} + \overline{B}$$

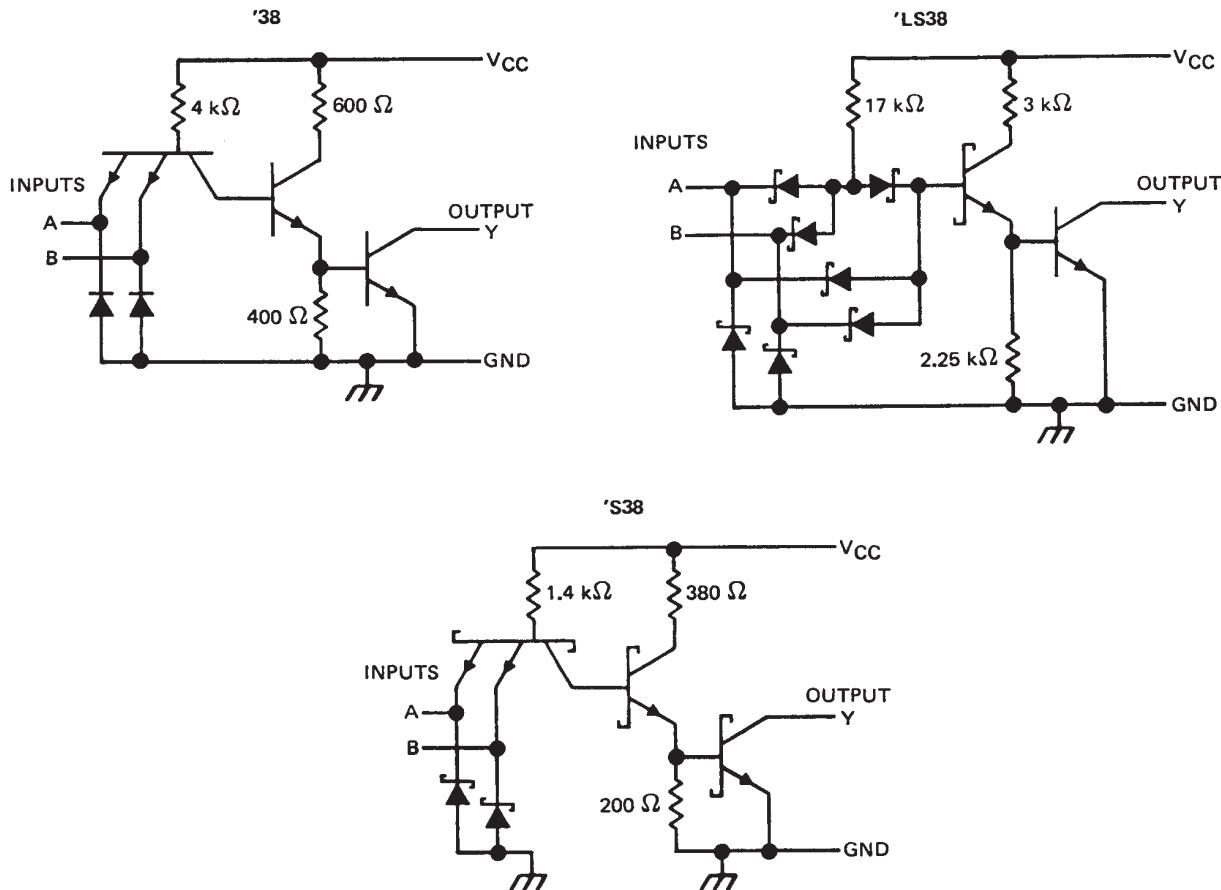
SN5438, SN54LS38, SN54S38

SN7438, SN74LS38, SN74S38

QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS

SDLS105 – DECEMBER 1983 – REVISED MARCH 1988

schematics (each gate)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage: '38	5.5 V
LS38	7 V
Off-state output voltage	7 V
Operating free-air temperature range: SN54'	-55°C to 125°C
SN74'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN5438, SN54LS38, SN54S38
SN7438, SN74LS38, SN74S38

QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS

SDLS105 – DECEMBER 1983 – REVISED MARCH 1988

recommended operating conditions

	SN5438			SN7438			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.8			0.8	V
V _{OH} High-level output voltage			5.5			5.5	V
I _{OL} Low-level output current			48			48	mA
T _A Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]	SN5438			SN7438			UNIT	
		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX		
V _{IK}	V _{CC} = MIN, I _I = -12 mA			-1.5			-1.5	V	
I _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, V _{OH} = 5.5 V						0.25	mA	
	V _{CC} = MIN, V _{IL} = 0.7 V, V _{OH} = 5.5 V			0.25					
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 16 mA			0.4			0.4	V	
I _I	V _{CC} = MAX, V _I = 5.5 V			1			1	mA	
I _{IH}	V _{CC} = MAX, V _I = 2.4 V			40			40	μA	
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			-1.6			-1.6	mA	
I _{CCH}	V _{CC} = MAX, V _I = 0			5	8.5		5	8.5	mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V			34	54		34	54	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A or B	Y	R _L = 133 Ω, C _L = 45 pF	14	22		ns
t _{PHL}				11	18		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN5438, SN54LS38, SN54S38

SN7438, SN74LS38, SN74S38

QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS

SDLS105 – DECEMBER 1983 – REVISED MARCH 1988

recommended operating conditions

	SN54LS38	SN74LS38			UNIT
		MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5 5.25
V _{IH} High-level input voltage	2			2	V
V _{IL} Low-level input voltage			0.7		0.8
V _{OH} High-level output voltage			5.5		5.5
I _{OL} Low-level output current			12		24 mA
T _A Operating free-air temperature	-55		125	0	70 °C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †	SN54LS38			SN74LS38			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V _{IK}	V _{CC} = MIN, I _I = -18 mA			-1.5			-1.5	V
I _{OH}	V _{CC} = MIN, V _{IL} = MAX, V _{OH} = 5.5 V			0.25			0.25	mA
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 12 mA		0.25	0.4	0.25	0.4		V
	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 24 mA				0.35	0.5		
I _I	V _{CC} = MAX, V _I = 7 V			0.1			0.1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.7 V			20			20	μA
I _{IL}	V _{CC} = MAX, V _I = 0.4 V			-0.4			-0.4	mA
I _{CCH}	V _{CC} = MAX, V _I = 0		0.9	2	0.9	2		mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V		6	12	6	12		mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A or B	Y	R _L = 667 Ω, C _L = 45 pF	20	32		ns
t _{PHL}				18	28		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN5438, SN54LS38, SN54S38
SN7438, SN74LS38, SN74S38

QUADRUPLE 2-INPUT POSITIVE-NAND BUFFERS WITH OPEN-COLLECTOR OUTPUTS

SDLS105 – DECEMBER 1983 – REVISED MARCH 1988

recommended operating conditions

		SN54S38			SN74S38			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
V _{OH}	High-level output voltage			5.5			5.5	V
I _{OL}	Low-level output current			60			60	mA
T _A	Operating free-air temperature	–55	125	0	70		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS [†]	SN54S38			SN74S38			UNIT
		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V _{IK}	V _{CC} = MIN, I _I = –18 mA			–1.2			–1.2	V
I _{OH}	V _{CC} = MIN, V _{IL} = 0.8 V, V _{OH} = 5.5 V						0.25	mA
	V _{CC} = MIN, V _{IL} = 0.7 V, V _{OH} = 5.5 V			0.25				
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 60 mA			0.5			0.5	V
I _I	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
I _{IH}	V _{CC} = MAX, V _I = 2.4 V			0.1			0.1	mA
I _{IL}	V _{CC} = MAX, V _I = 0.5 V			–4			–4	mA
I _{CCH}	V _{CC} = MAX, V _I = 0	20	36		20	36		mA
I _{CCL}	V _{CC} = MAX, V _I = 4.5 V	46	80		46	80		mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡]All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	A or B	Y	R _L = 93 Ω, C _L = 50 pF	6.5	10	ns	
t _{PHL}				6.5	10	ns	
t _{PLH}			R _L = 93 Ω, C _L = 150 pF	9		ns	
t _{PHL}				8.5		ns	

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/00303BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30203B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30203B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30203BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30203BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30203BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30203BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN5438J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN5438J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS38J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS38J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S38J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S38J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN7438D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN7438J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN7438N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7438N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7438N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7438N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7438NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7438NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN7438NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN7438NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS &	CU NIPDAU	Level-1-260C-UNLIM

PACKAGE OPTION ADDENDUM

26-Sep-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
no Sb/Br)								
SN7438NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS38DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS38DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS38N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS38N3	OBsolete	PDIP	N	14	TBD		Call TI	Call TI
SN74LS38N3	OBsolete	PDIP	N	14	TBD		Call TI	Call TI
SN74LS38NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS38NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS38NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS38NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

PACKAGE OPTION ADDENDUM

26-Sep-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74S38DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S38N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S38N3	OBsolete	PDIP	N	14		TBD	Call TI	Call TI
SN74S38N3	OBsolete	PDIP	N	14		TBD	Call TI	Call TI
SN74S38NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S38NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74S38NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S38NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5438J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5438J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5438W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5438W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS38FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS38FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS38J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS38J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS38W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS38W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S38FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S38FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S38J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S38J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S38W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S38W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

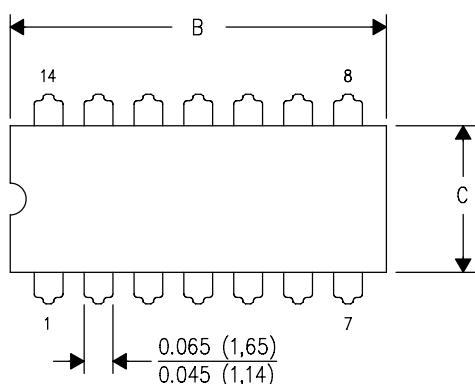
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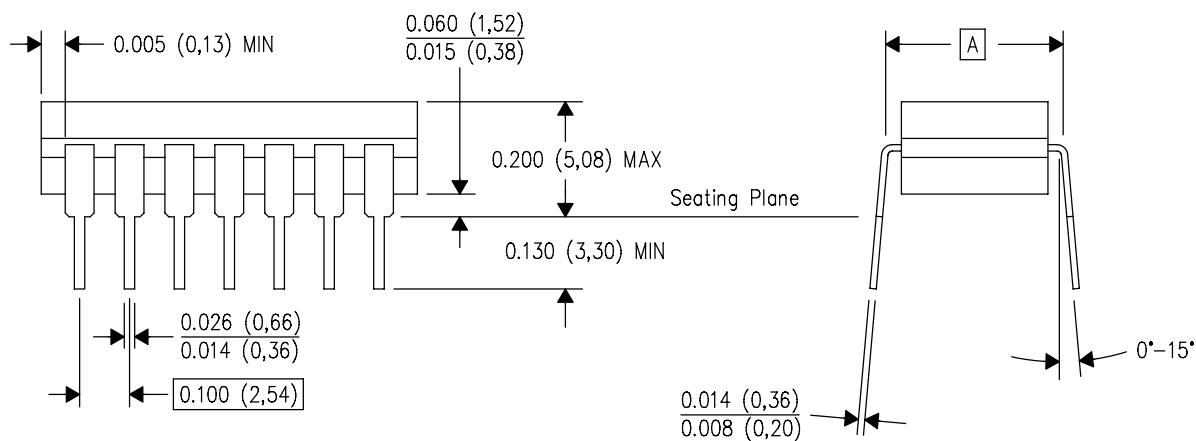
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



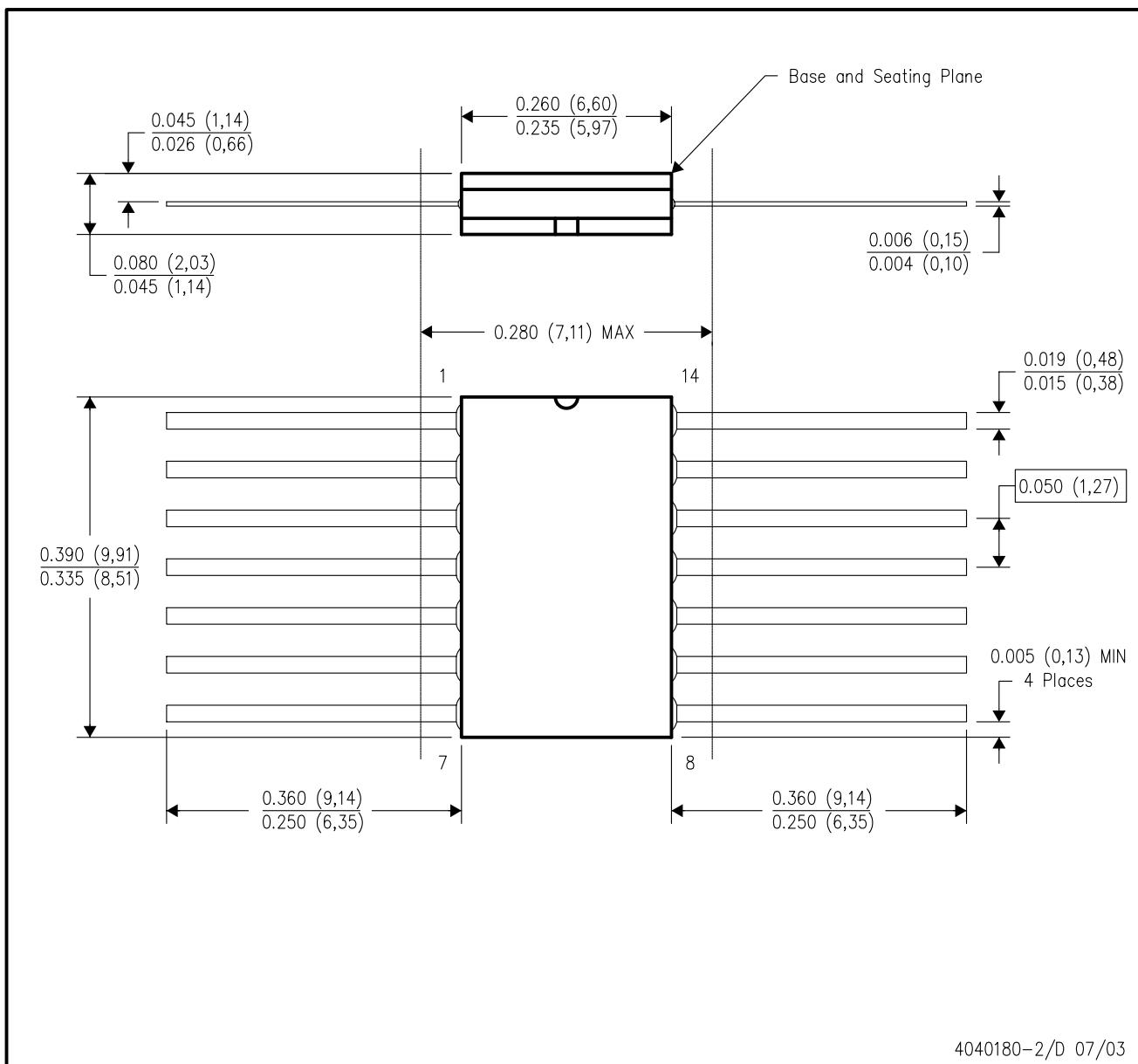
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

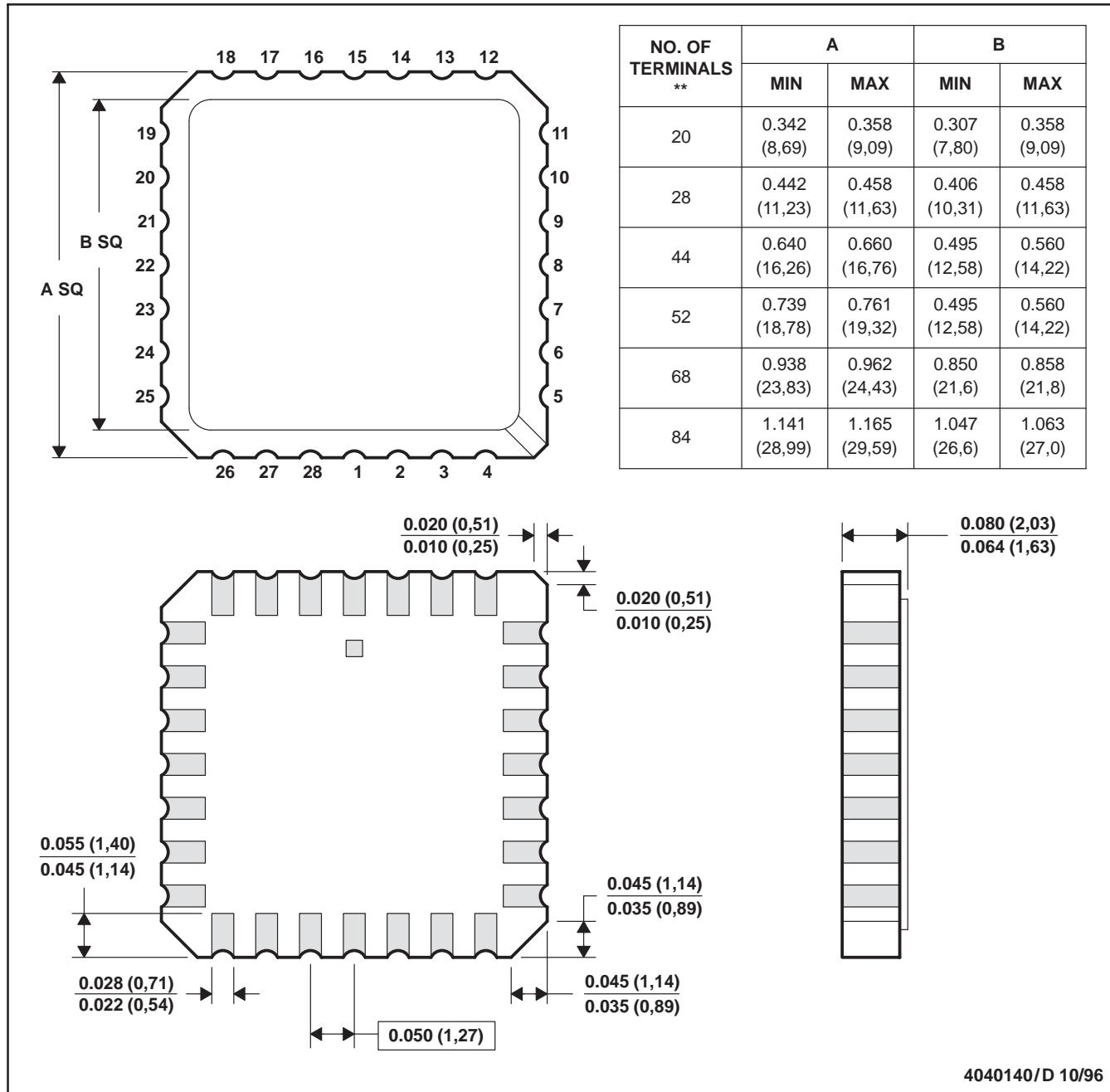
MECHANICAL DATA

MLCC006B – OCTOBER 1996

FK (S-CQCC-N)**

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



4040140/D 10/96

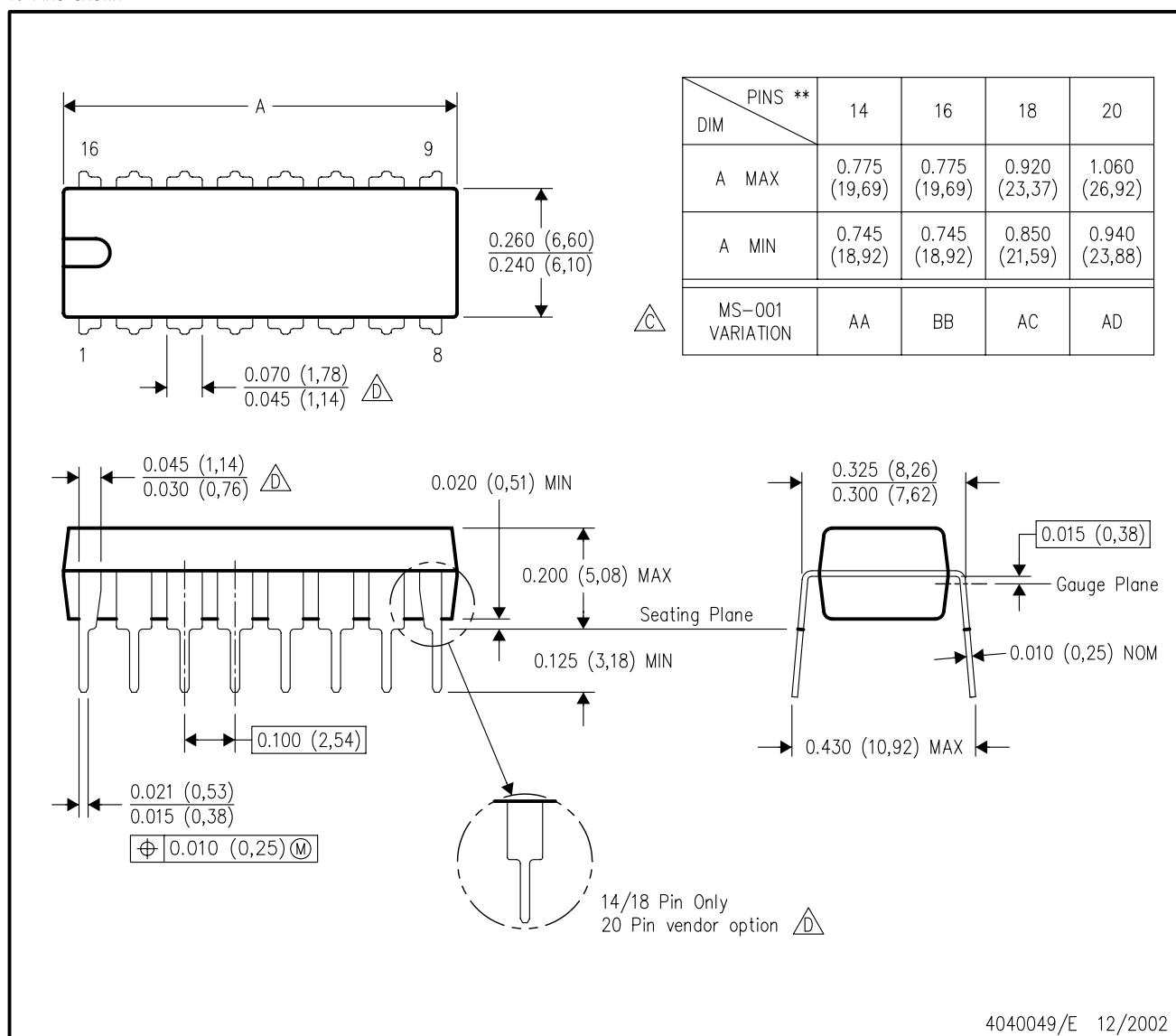
- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a metal lid.
 D. The terminals are gold plated.
 E. Falls within JEDEC MS-004

MECHANICAL DATA

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



4040049/E 12/2002

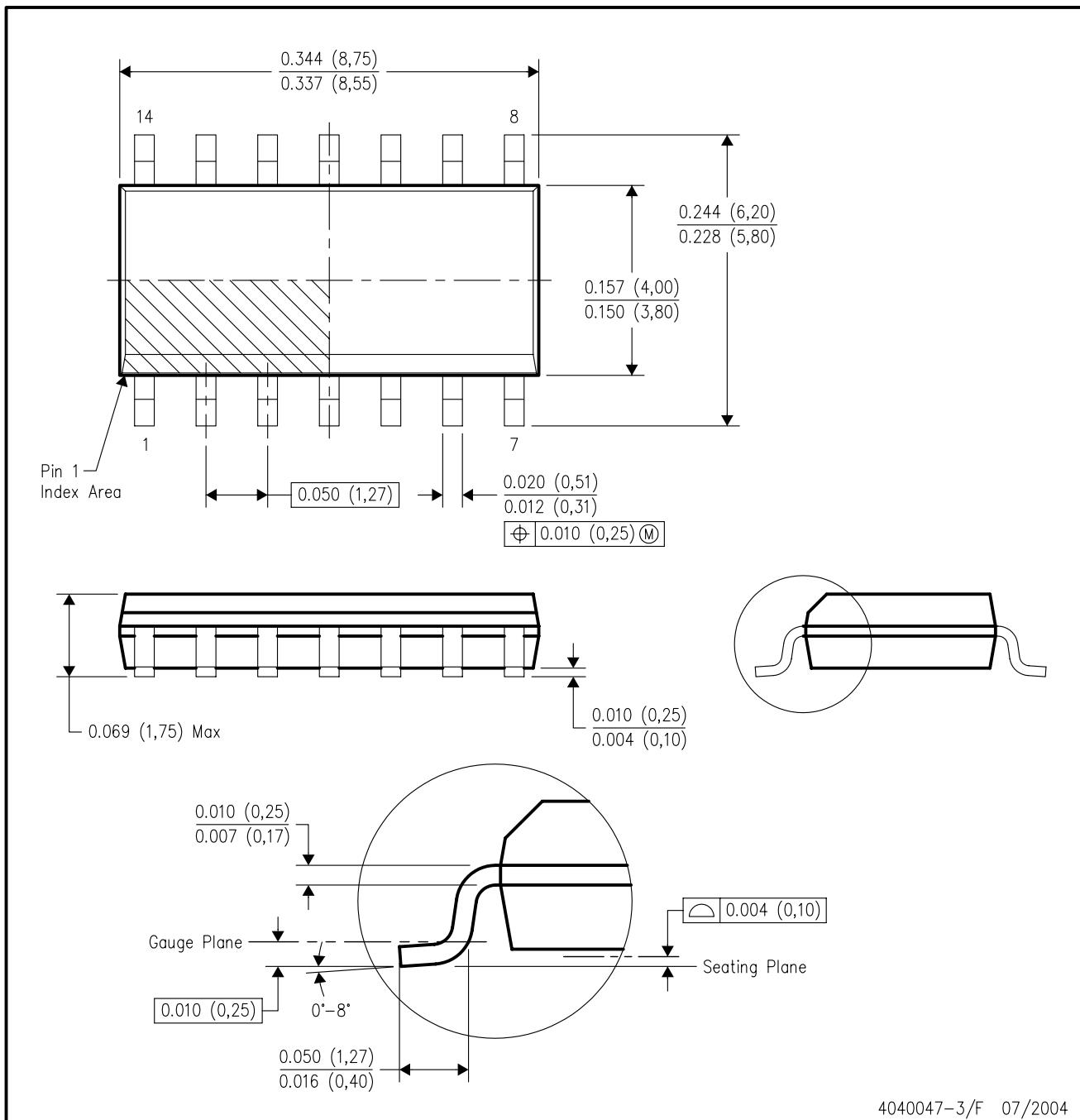
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/F 07/2004

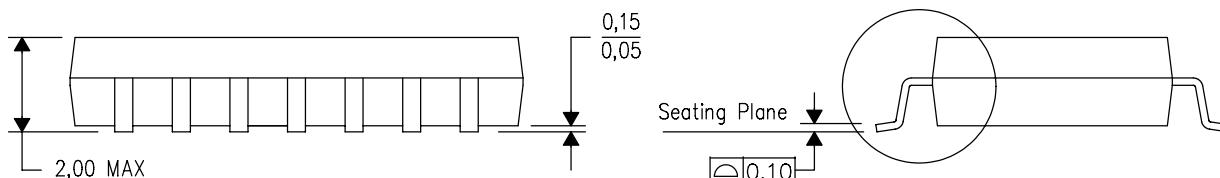
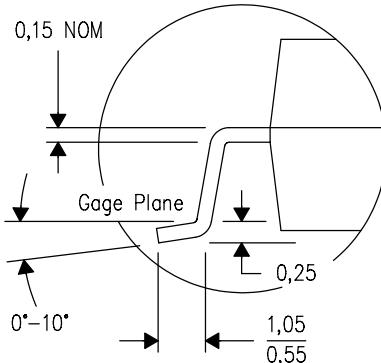
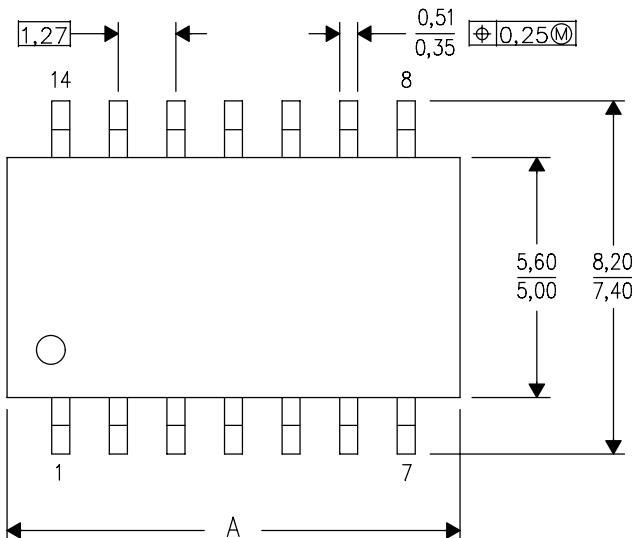
- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AB.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



PINS ** DIM	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

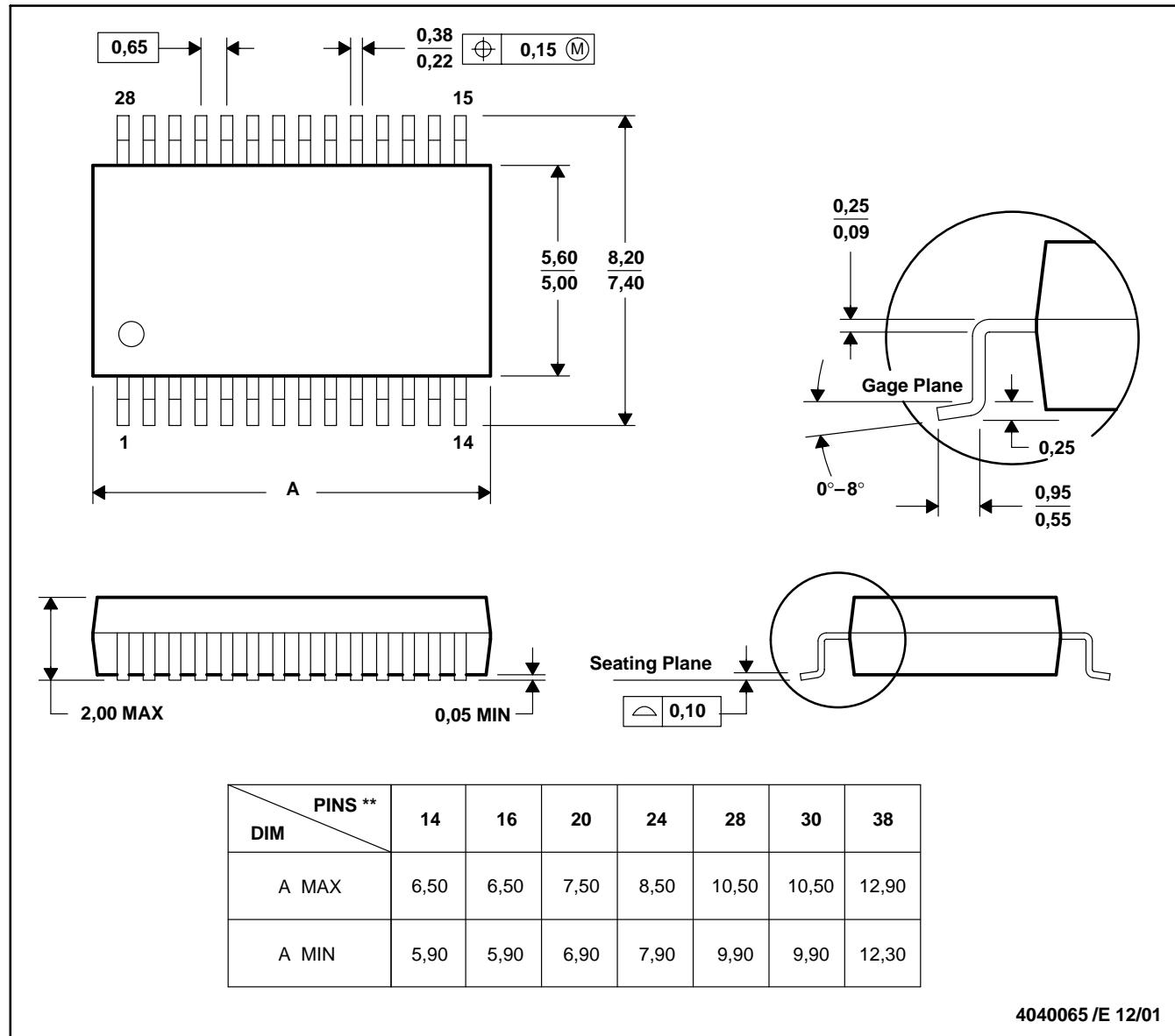
MECHANICAL DATA

MSS002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)**

28 PINS SHOWN

PLASTIC SMALL-OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - D. Falls within JEDEC MO-150

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